

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5348631

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
FONG-YUAN CHANG	11/26/2018
KUO-NAN YANG	11/26/2018
CHUNG-HSING WANG	11/28/2018
LEE-CHUNG LU	11/28/2018
SHENG-FONG CHEN	11/27/2018
PO-HSIANG HUANG	11/26/2018
HIRANMAY BISWAS	01/23/2019
SHENG-HSIUNG CHEN	11/26/2018
AFTAB ALAM KHAN	11/26/2018
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO.8, LI-HSIN RD.6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16122762
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4352521360
Email:	gschneider@mabr.com
Correspondent Name:	R. BURNS ISRAELSEN
Address Line 1:	MASCHOFF BRENNAN
Address Line 2:	1389 CENTER DR. SUITE 300
Address Line 4:	PARK CITY, UTAH 84098
ATTORNEY DOCKET NUMBER:	T1516.10401US02

PATENT

NAME OF SUBMITTER:	R. BURNS ISRAELSEN
SIGNATURE:	/R. Burns Israelsen, Reg. No. 42685/
DATE SIGNED:	01/29/2019
Total Attachments: 4 source=T1516-10401US02_Assignment#page1.tif source=T1516-10401US02_Assignment#page2.tif source=T1516-10401US02_Assignment#page3.tif source=T1516-10401US02_Assignment#page4.tif	

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) _____
INTEGRATED CIRCUIT AND METHOD OF GENERATING INTEGRATED CIRCUIT
LAYOUT

The PATENT RIGHTS referred to in this agreement are:

(check one) a patent application for this invention, executed by the ASSIGNOR(S)
concurrently with this assignment.

U.S. patent application Serial No. 16/122,762, filed September 5, 2018

a U.S. patent application based on PCT International Application

No. _____ filed on (date) _____ (U.S. patent application
Serial No. _____, if known).

U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of
the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(check one) U.S. patent rights only.

Worldwide patent rights. In this case, the assignee shall have the right to
claim the benefit of the filing date of any U.S. or foreign patent application
for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures
appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.

(Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,
TAIWAN 300, R.O.C.

The ASSIGNEE is:

(check one) An individual.

A Partnership.

A Corporation of TAIWAN, R.O.C. (specify state or country)

(other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and
valuable consideration, receipt of which is acknowledged, hereby assign(s) the following
rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable
provisions, based on any earlier patent applications for this invention.

NP-21201-US/P20170754US00

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO
 ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
 INVENTION TITLE: INTEGRATED CIRCUIT AND METHOD OF
 GENERATING INTEGRATED CIRCUIT LAYOUT

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

<u>Fong-Yuan CHANG</u> ✓ Name of sole or first inventor	<u>Fong-Yuan Chang</u> Signature	<u>2018/11/26</u> Date
<u>Kuo-Nan YANG</u> ✓ Name of second inventor, if any	<u>Kuo-Nan Yang</u> Signature	<u>2018/11/26</u> Date
<u>Chung-Hsing WANG</u> ✓ Name of third inventor, if any	<u>Chung-Hsing Wang</u> Signature	<u>11/28/2018</u> Date
<u>Lee-Chung LU</u> ✓ Name of fourth inventor, if any	<u>Lee-Chung Lu</u> Signature	<u>2018/11/28</u> Date
<u>Sheng-Fong CHEN</u> ✓ Name of fifth inventor, if any	<u>Sheng-Fong Chen</u> Signature	<u>2018/11/27</u> Date
<u>Po-Hsiang HUANG</u> ✓ Name of sixth inventor, if any	<u>Po-Hsiang HUANG</u> Signature	<u>2018/11/26</u> Date
<u>Hiranmay BISWAS</u> Name of seventh inventor, if any	 Signature	 Date

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO
 ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
 INVENTION TITLE: INTEGRATED CIRCUIT AND METHOD OF
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Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representative, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Fong-Yuan CHANG

Name of sole or first inventor Signature Date

Kuo-Nan YANG

Name of second inventor, if any Signature Date

Chung-Hsing WANG

Name of third inventor, if any Signature Date

Lee-Chung LU

Name of fourth inventor, if any Signature Date

Sheng-Fong CHEN

Name of fifth inventor, if any Signature Date

Po-Hsiang HUANG

Name of sixth inventor, if any Signature Date

Hiranmay BISWAS

Name of seventh inventor, if any Signature Date

Hiranmay Biswas

2019/01/23

NP-21201-US/P20170754US00

Sheng-Hsiung CHEN ✓
Name of eighth inventor, if any

Sheng Hsiung Chen
Signature

2018/11/26
Date

Aftab Afam KHAN ✓
Name of ninth inventor, if any

Aftab
Signature

2018/11/26
Date